

REMARKS**1. Present Status of Patent Application**

This is a full response to the outstanding final Office Action, mailed January 10, 2006. Reconsideration and allowance of the application and presently pending claims 1-8 and 16-27 are respectfully requested.

2. Response to Rejection of Claims Under 35 U.S.C. 102(e)

Claims 1, 3-6, 16, 20-24, and 26 were rejected under 35 U.S.C. §102(e) as allegedly being anticipated by *Yamaguchi* (U.S. Patent No. 6,166,430). For a proper rejection of a claim under 35 U.S.C. Section 102(e), the cited reference must disclose all elements/features/steps of the claim. See, e.g., *E.I. du Pont de Nemours & Co. v. Phillips Petroleum Co.*, 849 F.2d 1430, 7 USPQ2d 1129 (Fed. Cir. 1988).

a. Claim 1

As provided in independent claim 1, Applicants claim:

A method for forming a package for an electrical device, said method comprising the steps of:

attaching a removable material to a surface of conductive material before one or more isolated conductive features have been formed within said conductive material;

forming said isolated conductive features within said conductive material;
attaching encapsulant to said isolated conductive features and said removable material, wherein said attaching step is performed before a singulation process is performed to separate said package; and

removing said removable material from said conductive features and said encapsulant, wherein the removing said material step is performed after the singulation process is performed to separate said package.

(Emphasis added).

Applicants respectfully submit that independent claim 1 is allowable for at least the reason that *Yamaguchi* does not disclose, teach, or suggest "attaching a removable material to a surface of conductive material before one or more isolated conductive features have been formed within said conductive material," as recited and emphasized above in claim 1.

Yamaguchi is apparently limited, at most, to an approach for manufacturing a semiconductor device where "a metal plate for lead frame 21 made of copper, for example, is etched or pressed" and "a pad assembly 16 including die pads 14, connection portions 16a and a frame 16 is formed by etching or pressing another metal plate. . . . Subsequently, in the process step . . . a plastic film 12 . . . is attached to the lower surface of the main lead frame unit." See col. 8, lines 22-54. Therefore, *Yamaguchi* fails to disclose, teach, or suggest "attaching a removable material to a surface of conductive material before one or more isolated conductive features have been formed within said conductive material."

For at least these reasons, the rejection of claim 1 should be withdrawn.

b. Claims 3-6, 16, 20-24, and 26

Dependent claims 3-6, 16, 20-24, and 26 are believed to be allowable for at least the reason that these claims depend from allowable independent claim 1. *In re Fine*, 837 F.2d 1071, 5 U.S.P.Q.2d 1596, 1600 (Fed. Cir. 1988).

3. Response to Rejection of Claims Under 35 U.S.C. 103(a)

Claims 1-6, 16, 20-24, and 26 have been rejected under 35 U.S.C. §103(a) as purportedly being unpatentable over *Glenn* (U.S. Patent No. 6,247,229) in view of *Yamaguchi*. Claims 7-8 and 17 have been rejected under 35 U.S.C. §103(a) as purportedly being unpatentable over *Glenn* (U.S. Patent No. 6,247,229) in view of *Yamaguchi* in further view of *Wyland* (U.S. Patent No. 6,111,199) in further view of *Weng* (U.S. Patent No. 5,972,234). Claims 25 and 27 have been rejected under 35 U.S.C. §103(a) as purportedly being unpatentable over *Glenn* in view of *Yamaguchi* in further view of *Fjelstad* (U.S. Patent No. 6,001,671).

In order for a claim to be properly rejected under 35 U.S.C. §103, the teachings of the cited art reference must suggest all features of the claimed invention to one of ordinary skill in the art. See, e.g., *In re Dow Chemical*, 837 F.2d 469, 5 U.S.P.Q.2d 1529, 1531 (Fed. Cir. 1988); *In re Keller*, 642 F.2d 413, 208 U.S.P.Q. 871, 881 (C.C.P.A. 1981).

Applicants submit that *Glenn* does not teach or suggests all of the claimed features of independent claim 1. Further, Applicants submit that the cited art in the proposed combinations fails to cure the deficiencies of the *Glenn* reference.

For example, *Glenn* is apparently limited, at most, to an approach for forming packages for housing an integrated circuit device. In *Glenn*, step 9 of FIG. 1 clearly shows that individual packages are separated from an encapsulated array after plastic sheet 10 is removed from the encapsulated array in step 7. See cols. 5-6, lines 48-7. Therefore, *Glenn* fails to disclose, teach, or suggest "removing said removable material from said conductive features and said encapsulant, wherein the removing said material step is performed after the singulation process is performed to separate said package."

Glenn teaches that "Step 9 may be performed, for example by cutting encapsulated array with a saw. Disposable material, such as bead 33 is cut away." The bead 33 is formed onto a first surface 11 of plastic sheet 10. See col. 5, lines 6-29 and col. 6, lines 4-71. Therefore, *Glenn* seemingly teaches that the plastic sheet 10 is to be removed before the bead 33 is cut away in a singulation process. As such, the teachings of *Glenn* do not appear to allow modifications to be made to suggest or disclose the claimed subject matter. For at least this reason, the cited art in the proposed combinations fails to cure the deficiencies of the *Glenn* reference.

Thus, claim 1 and claims 2-8, 16-17, and 20-27 (which depend from respective independent claim 1) are allowable for at least this reason.

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PAGE 10

Serial No. 10/649,577
Art Unit: 2822

CONCLUSION

For at least the reasons set forth above, Applicants respectfully submit that all objections and/or rejections have been traversed, rendered moot, and/or accommodated, and that the pending claims are in condition for allowance. Favorable reconsideration and allowance of the present application and all pending claims are hereby courteously requested. If, in the opinion of the Examiner, a telephonic conference would expedite the examination of this matter, the Examiner is invited to call the undersigned agent at (770) 933-9500.

Respectfully submitted,


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